



VMDSEMI

VUSB002R570PA

Datasheet

General Description

VUSB002R570PA MOSFET is based on unique device design to achieve low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics.

Symbol

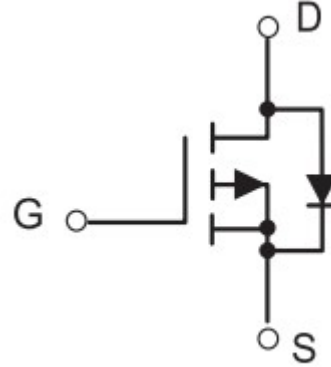


Figure 1 Symbol of VUSB002R570PA

Features

- Trench Technology Power MOSFET
- $R_{DS(ON)_{max}} = 57.0m\Omega @ V_{GS} = -4.5V$
- Low Gate Charge

Application

- Power switching application
- Load Switch
- DC/DC Converter

Package Type

SOT-23

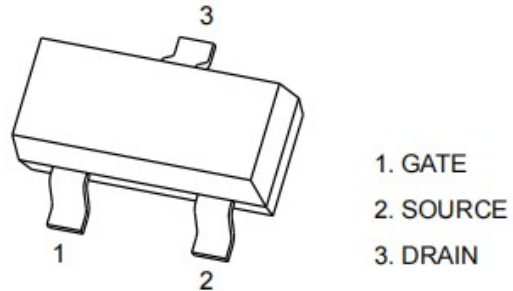


Figure 2 Package Type of VUSB002R570PA

Ordering Information

Product Name	Package
VUSB002R570PA	SOT-23

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	±12	V
Continuous Drain Current ^{Note1,5} $T_A = 25^\circ\text{C}$	I_D	-3.8	A
Pulsed Drain Current ^{Note2}	I_{DM}	-15	A
Max Power Dissipation ^{Note4,5} $T_A = 25^\circ\text{C}$	P_D	1.3	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note5}	$R_{\theta JA}$		96		°C/W

Electrical Characteristics $T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-16V, V_{GS}=0V$			-1	μA
Gate-Body Leakage Current	Forward	$I_{GSSF}, V_{GS}=-12V$			100	nA
	Reverse	$I_{GSSR}, V_{GS}=12V$			-100	
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.7	-1	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-3.3A$		35	57	$m\Omega$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=-2.5V, I_D=-2.8A$		49	76	$m\Omega$
Gate Resistance	R_g	$V_{DS}=0V, V_{GS}=0V, f=1MHz$		25		Ω
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=-10V$		1003		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		137		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		123		pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DS}=-6V$			25	ns
Rise Time	t_r	$V_{GS}=-4.5V$			55	
Turn-off Delay Time	$t_{d(off)}$	$I_D=-1A$			90	
Fall Time	t_f	$R_G=6.0\Omega$			60	
Gate Charge Characteristics						
Gate to Source Charge	Q_{gs}	$V_{DS}=-10V$		1.4		nC
Gate to Drain Charge	Q_{gd}	$V_{GS}=-4.5V$		3		
Gate Charge Total	Q_g	$I_D=-3.3A$		11		
Diode Characteristics						
Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_{SD}=-1.6A$			-1.2	V

Notes :

- 1.The maximum current rating is limited by package.
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 4.The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$.
- 5.Device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Performance Characteristics

Figure 3: Transfer Characteristics

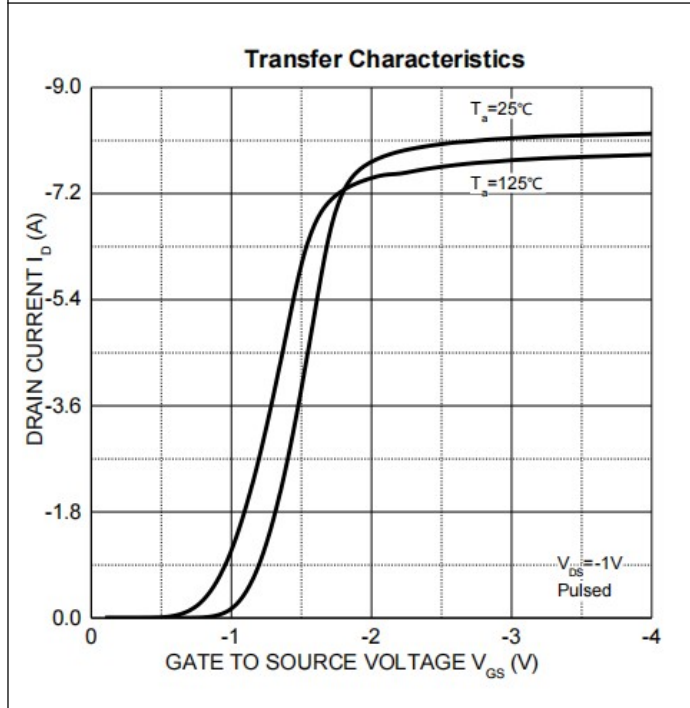


Figure 4: Typ. Output Characteristics

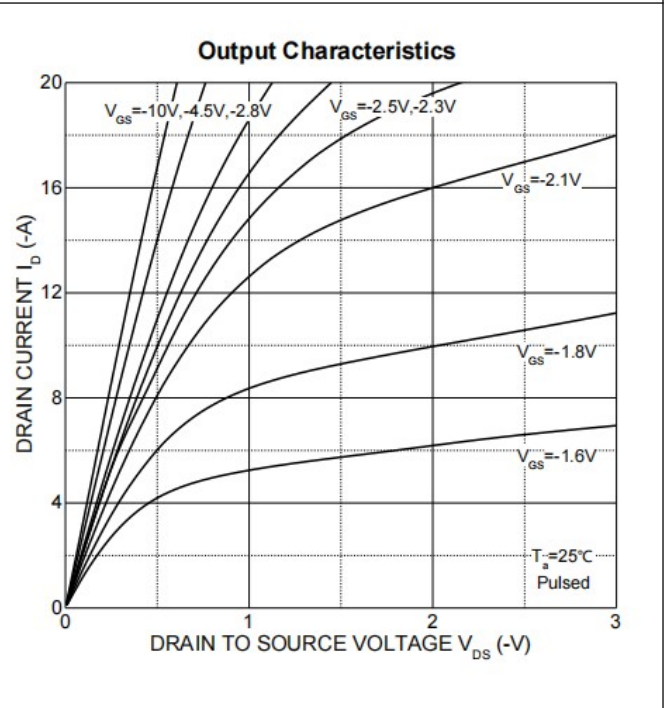
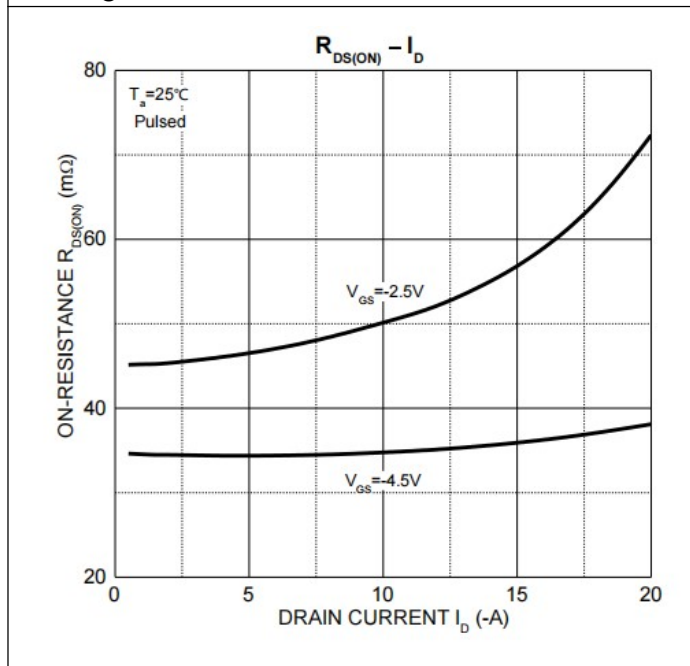
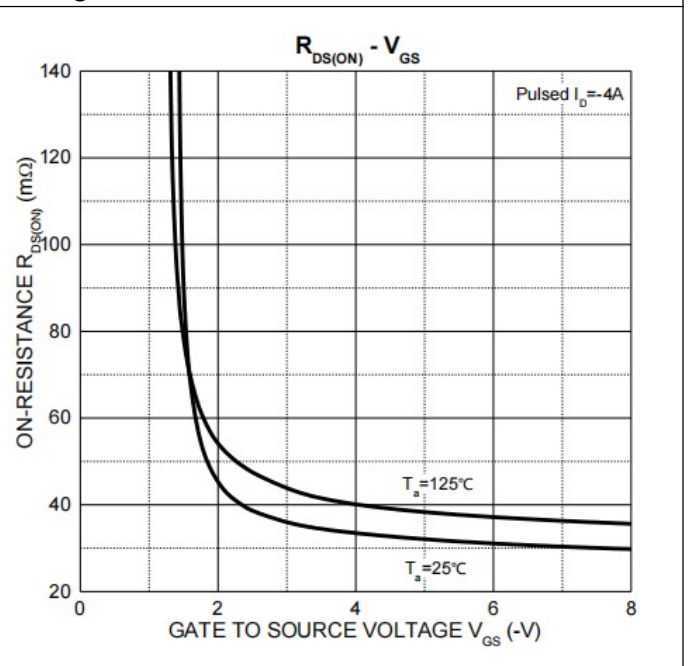
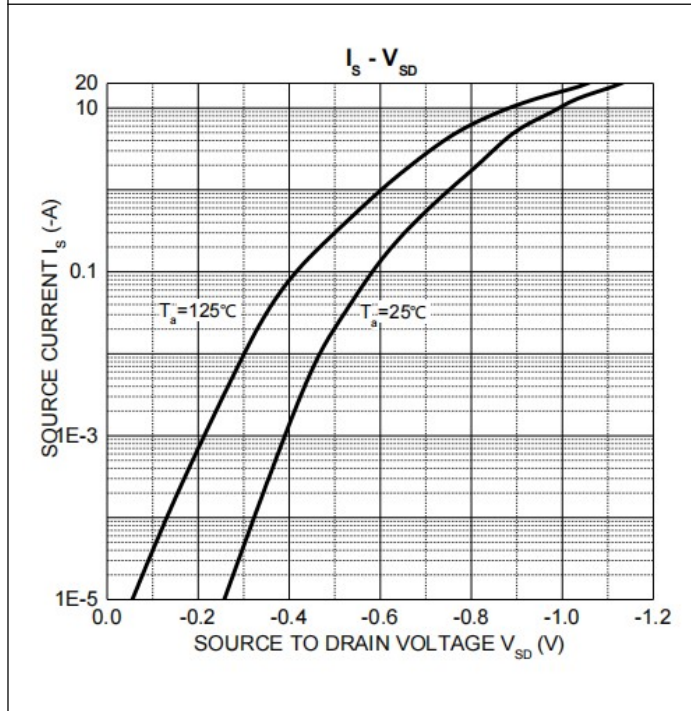
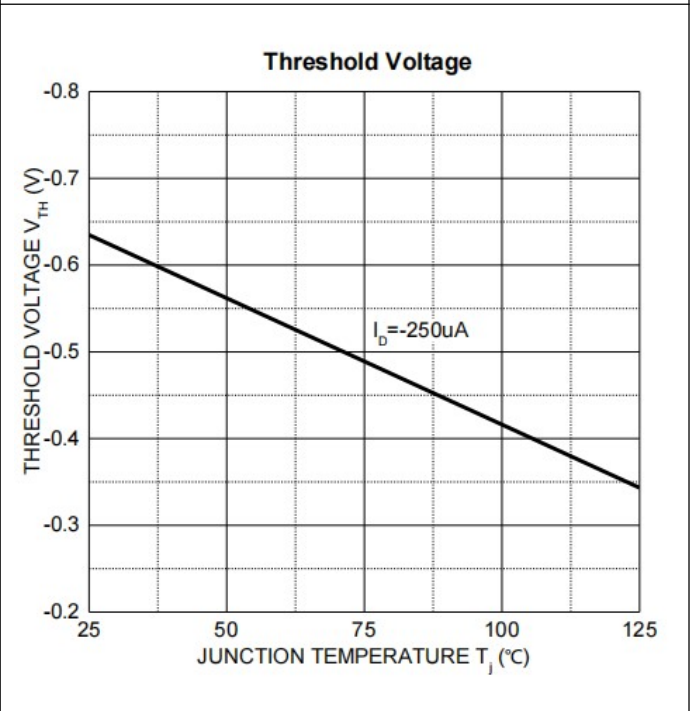
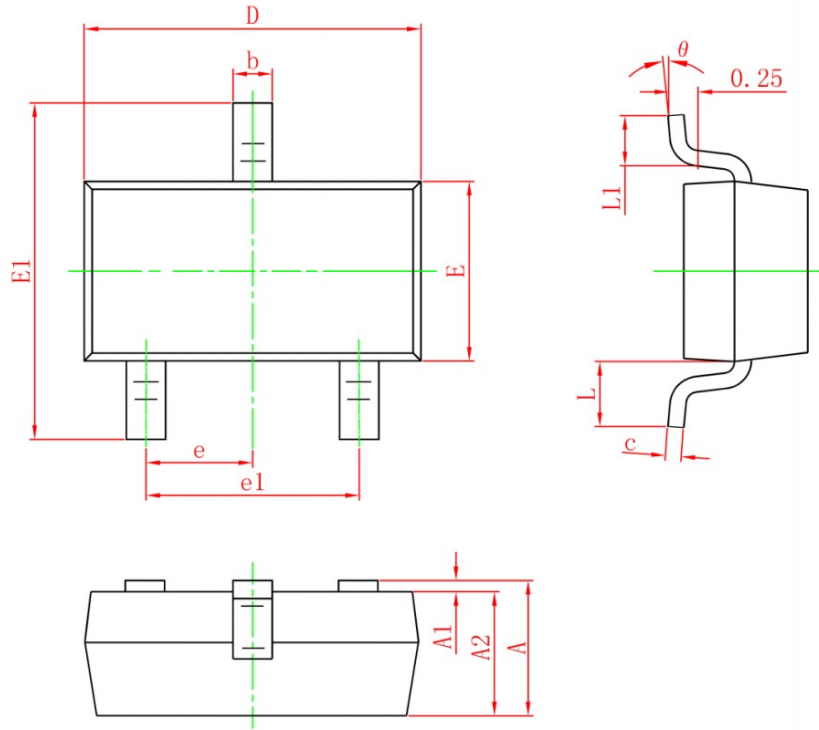

 Figure 5: Drain-Source On-State Resistance- I_D

 Figure 6: Drain-Source On-State Resistance - V_{GS}


Figure 7: Source Current

Figure 8: Threshold Voltage


Mechanical Dimensions:


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.150	1.500	0.045	0.059
E1	2.250	2.650	0.089	0.104
e	0.950REF		0.037REF	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

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